L	Hits	Search Text	DB	Time stamp
Number				
7	45464	,	USPAT;	2004/03/19
		dielectric)	US-PGPUB;	17:29
			EPO; JPO;	
1			DERWENT;	
l _			IBM_TDB	
8	4443653	via hole plug stud	USPAT;	2004/03/19
			US-PGPUB;	17:30
			EPO; JPO;	
			DERWENT;	
1	400400		IBM_TDB	2004/02/10
9	490420	pad	USPAT;	2004/03/19
			US-PGPUB;	17:30
		•	EPO; JPO;	
			DERWENT;	
1.0	F 0.0 F	1/4-5	IBM_TDB	2004/02/10
10	5025	(,====================================	USPAT;	2004/03/19
		(insulat\$3 dielectric)) and (via hole	US-PGPUB;	17:31
	i	plug stud) and pad	EPO; JPO; DERWENT;	
			IBM TDB	
11	15433	bump near2 (electrode conduct\$3)	USPAT;	2004/03/19
1 1 1	13433	bump hearz (erectione conducts)	US-PGPUB;	17:32
			EPO; JPO;	17.52
			DERWENT;	
			IBM TDB	
12	234	(((interlayer inter-layer) near2	USPAT;	2004/03/19
	234	(insulat\$3 dielectric)) and (via hole	US-PGPUB;	17:32
		plug stud) and pad) and (bump near2	EPO; JPO;	
		(electrode conduct\$3))	DERWENT;	
		(02002000000000000000000000000000000000	IBM TDB	